

1 ABSTRACT OF THE INVENTION  
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3 A chip-scale sized package for acoustic wave devices,  
4 acoustic resonators and similar acoustic devices located upon, or  
5 fabricated upon, or as part of, a die. The package includes a lid  
6 that is bonded to the die by a strip of solder or other bonding  
7 material so as to leave a space between the lid and that portion  
8 of the die that acoustically deforms or vibrates. The upper  
9 surface of the lid includes electrical connectors that are  
10 electrically connected via plated through holes or other means to  
11 electrical connectors, or pads on the lower surface of the lid,  
12 which pads, in turn, are electrically connected by solder or other  
13 electrically conducting material to electrical connectors to the  
14 device that are located upon the surface of the die.

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